



CPC1035N 350V Normally-Open Single-Pole 4-Pin SOP OptoMOS[®] Relay

Parameter	Rating	Units
Blocking Voltage	350	V _P
Load Current	100	mA _{rms} / mA _{DC}
On-Resistance (max)	35	Ω

Features

- 1500V_{rms} Input/Output Isolation
- Small 4-Pin SOP Package
- Low Drive Power Requirements
- · High Reliability
- Arc-Free With No Snubbing Circuits
- No EMI/RFI Generation
- Halogen-Free
- Flammability Rating UL 94 V-0
- Tape & Reel Version Available

Applications

- Telecommunications
- Telecom Switching
- Tip/Ring Circuits
- Modem Switching (Laptop, Notebook, Pocket Size)
- · Hook Switch
- Dial Pulsing
- · Ground Start
- Ringing Injection
- Instrumentation
- Multiplexers
- Data Acquisition
- Electronic Switching
- I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- Medical Equipment—Patient/Equipment Isolation
- Security
- Aerospace
- Industrial Controls

Description

The CPC1035N is a miniature normally-open, single-pole, (1-Form-A) solid state relay in a 4-pin SOP package that employs optically coupled MOSFET technology to provide 1500V_{rms} of input to output isolation. The efficient MOSFET switches and photovoltaic die use IXYS Integrated Circuits Division's patented OptoMOS architecture while the optically coupled output is controlled by a highly efficient infrared LED.

IXYS Integrated Circuits Division's state of the art double-molded vertical construction packaging makes the CPC1035N one of the world's smallest relays. It offers board space savings of at least 20% over the competitor's larger 4-pin SOP relay.

Approvals

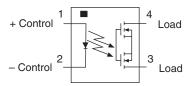
- UL Recognized Component: File E76270
- CSA Certified Component: Certificate 1172007
- EN/IEC 60950-1 Certified Component: Certificate B 13 12 82667 003

Ordering Information

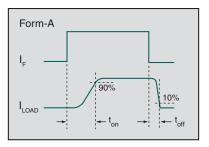
Part #	Description
CPC1035N	4-Pin SOP (100/tube)
CPC1035NTR	4-Pin SOP (2000/reel)

* For other packaging options consult factory.

Pin Configuration



Switching Characteristics of Normally-Open Devices







Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units
Blocking Voltage	350	V _P
Reverse Input Voltage	5	V
Input control Current	50	mA
Peak (10ms)	1	А
Input Power Dissipation	70	mW
Total Power Dissipation ¹	400	mW
Isolation Voltage, Input to Output	1500	V _{rms}
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Typical values are characteristic of the device at +25°C, and are the result of engineering evaluations. They are provided for information purposes only, and are not part of the manufacturing testing requirements.

 $^1\,$ Derate linearly 3.33 mW / $^{\rm o}{\rm C}$

Electrical Characteristics @ 25°C

Parameter	Conditions	Symbol	Min	Тур	Max	Units
Output Characteristics					1	
Load Current						
Continuous ¹	-	I,	-	-	100	mA _{rms} / mA _{DO}
Peak	t=10ms	I _{LPK}	-	-	±350	mA _P
On-Resistance ²	I ₁ =100mA	R _{ON}	-	30	35	Ω
Off-State Leakage Current	V ₁ =350V _P	ILEAK	-	-	1	μΑ
Switching Speeds						
Turn-On	L Em ()/ 10)/	t _{on}	-	-	2	
Turn-Off	I _F =5mA, V _L =10V	t _{off}	-	-	1	ms
Output Capacitance	I _F =0mA, V _L =50V, f=1MHz	C _{OUT}	-	9	-	pF
Input Characteristics						
Input Control Current to Activate ³	I _L =100mA	I _F	-	0.8	2	mA
Input Control Current to Deactivate	-	I _F	0.3	0.7	-	mA
Input Voltage Drop	I _F =5mA	V _F	0.9	1.2	1.5	V
Reverse Input Current	V _R =5V	I _B	-	-	10	μΑ
Input to Output Characteristics	S					
Capacitance, Input to Output	V _{IO} =0V, f=1MHz	CIO	-	0.7	1.45	pF

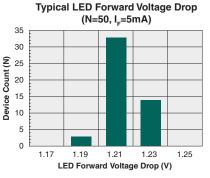
¹ Load current derates linearly from 100mA @ 25°C to 70mA @85°C. ² Massurement taken within 1 second of on time.

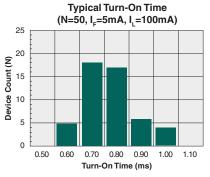
² Measurement taken within 1 second of on-time.
³ For applications requiring high temperature operation (greater than 60°C) a minimum LED drive current of 4mA is recommended.

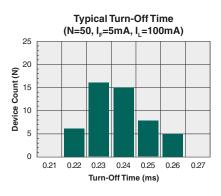


CPC1035N

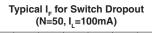
PERFORMANCE DATA*

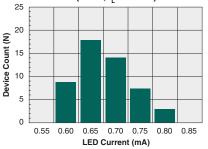




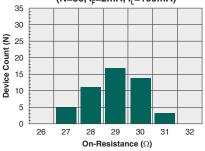


Typical I_F for Switch Operation (N=50, I,=100mÅ) 25 20 Device Count (N) 15 10 5 0 0.55 0.60 0.65 0.70 0.75 0.80 0.85 LED Current (mA)

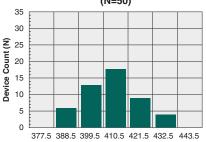




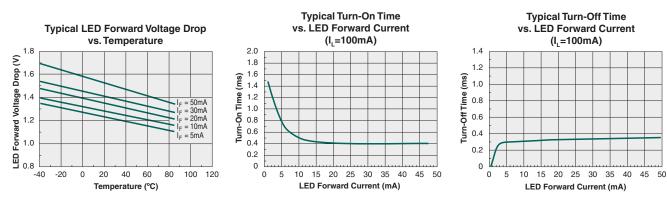
Typical On-Resistance Distribution (N=50, I_F=2mA, I_L=100mA)



Typical Blocking Voltage Distribution (N=50)



Blocking Voltage (V_P)



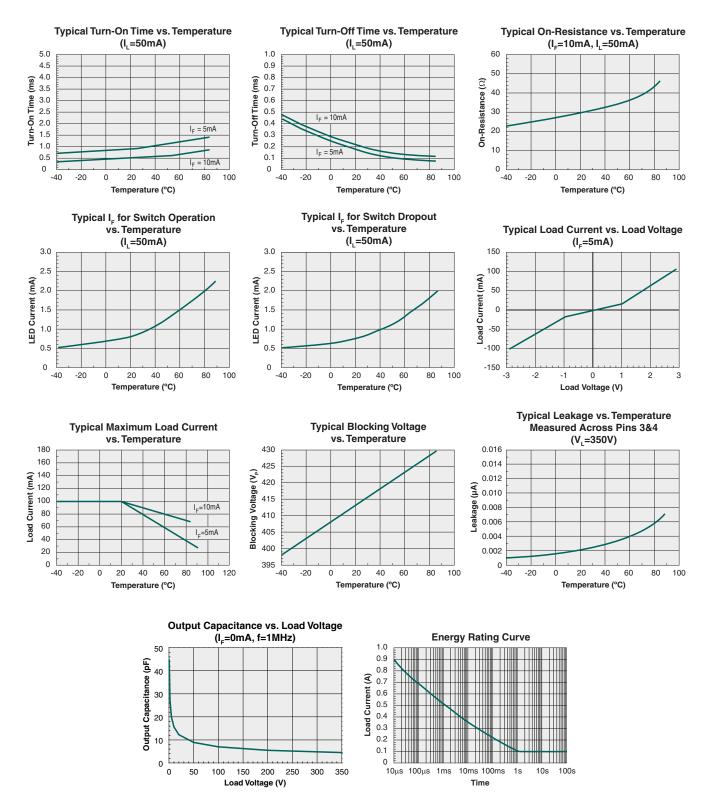
*Unless otherwise noted, data presented in these graphs is typical of device operation at 25°C. For guaranteed parameters not indicated in the written specifications, please contact our application department.

3



CPC1035N

PERFORMANCE DATA*



*Unless otherwise noted, data presented in these graphs is typical of device operation at 25°C. For guaranteed parameters not indicated in the written specifications, please contact our application department.

Manufacturing Information

Moisture Sensitivity

All plastic encapsulated semiconductor packages are susceptible to moisture ingression. IXYS Integrated Circuits Division classifies its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a Moisture Sensitivity Level (MSL) classification as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Classification		
CPC1035N	MSL 3		

ESD Sensitivity



This product is ESD Sensitive, and should be handled according to the industry standard JESD-625.

Soldering Profile

Provided in the table below is the Classification Temperature (T_c) of this product and the maximum dwell time the body temperature of this device may be $(T_c - 5)^{\circ}C$ or greater. The classification temperature sets the Maximum Body Temperature allowed for this device during lead-free reflow processes. For through-hole devices, and any other processes, the guidelines of **J-STD-020** must be observed.

Device	Classification Temperature (T _c)	Dwell Time (t _p)	Max Reflow Cycles
CPC1035N	260°C	30 seconds	3

Board Wash

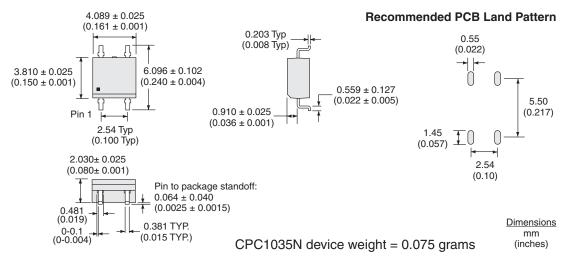
IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include, but are not limited to: using a low pressure wash and providing a follow up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device and should not be used. Additionally, the device must not be exposed to flux or solvents that are Chlorine- or Fluorine-based.



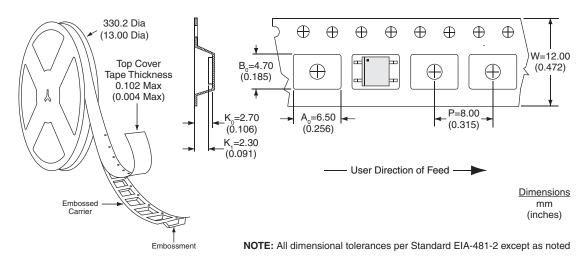


MECHANICAL DIMENSIONS

CPC1035N



CPC1035NTR Tape & Reel



For additional information please visit our website at: www.ixysic.com

IXYS Integrated Circuits Division makes no representations or warranties with respect to the accuracy or completeness of the contents of this publication and reserves the right to make changes to specifications and product descriptions at any time without notice. Neither circuit patent licenses nor indemnity are expressed or implied. Except as set forth in IXYS Integrated Circuits Division's Standard Terms and Conditions of Sale, IXYS Integrated Circuits Division assumes no liability whatsoever, and disclaims any express or implied warranty, relating to its products including, but not limited to, the implied warranty of merchantability, fitness for a particular purpose, or infrigement of any intellectual property right.

The products described in this document are not designed, intended, authorized or warranted for use as components in systems intended for surgical implant into the body, or in other applications intended to support or sustain life, or where malfunction of IXYS Integrated Circuits Division's product may result in direct physical harm, injury, or death to a person or severe property or environmental damage. IXYS Integrated Circuits Division reserves the right to discontinue or make changes to its products at any time without notice.